

CHEMICAL CLEAN & ETCH

MODELS CESx124 & 126

DESCRIPTION:

The **highly efficient** Models CESx124 & 126 are the ideal for Cleaning & Etching of Wafers & Substrates, & are configurable for Lift-Off processes. The **very reliable & cost-effective** systems utilize a proven assortment of technologies on individual or multiple media. They can be configured with several process dispense options from Brush for Sulfuric Peroxide, Surfactant, &/or DI-H₂O as well as for Surface Agitation to Expedite Reactions; Megasonic Nozzles for DI-H₂O or Chemistries; Low pressure & Mixing nozzles for chemistry dispenses; Heaters for chemistries & DI-H₂O; N₂ Assist & much more. The Rapid & Effective Drying technique combines Variable Spin Speeds; optional Heated DI-H₂O; & N₂ Assist.

FEATURES:

- Up to Nine-by-Nine Inch (9"²)/200mm Diameter Substrate Compatibility.
- Main Spindle Assembly having Brushless Servo Motor for precise speed control & indexing.
- Oscillating Dispense Arms with Recipe-Adjustable Speed & Travel Positions & programmable parabolic travel.
- Radially Exhausted Chamber for Maximum Laminar Flow with N₂ feed at Top of the lid.
- DI-H₂O Heater for Clean & Dry Assist.
- Process Chamber of FM4910 Compliant PVDF with PTFE coated Stainless Steel surfaces & stand-alone Polypropylene Cabinet with Stainless Steel Internal Frame & Integrated Secondary Containment with Leak Detection.
- Microprocessor Control Capable of Retaining Thirty (30) Recipes having thirty (30) Steps each in Memory.
- Rinse to pH of entire process area & substrate with interlocks to prohibit access to process area & control Drain & Spindle Speed till safe.
- Push Button Lid Open/Close.
- Touch Screen Graphic User Interface (GUI) with Ease of Programming & Security Lockouts with On-Screen Error Reporting.
- Drain Diverters for Chemical & House Drains.
- Designed to SEMI S2/S8 Guidelines Comprehensive Compact Footprint of 28" wide X 24" deep includes Integrated DI H₂O Heater; Chemical Storage; & Secondary Containment. Front Service Access for All Components. Dimensions do not include rear-facing Facilities Connections.



Model CESx124 System Cabinet



Example of Process Arms & 4"x4" to 9"x9" Adjustable Photomask Chuck

OPTIONS:

- Various sizes & types of chucks for Wafers, Photomask, & other Substrates.
- Auto Up/Down Oscillating Adjustable Self-Cleaning Brush Assembly for chemical, Surfactant, & DI-H₂O Dispenses.
- Oscillating Megasonic Nozzles & MegPies for DI-H₂O or Chemical Dispense Arm.
- Fixed or Oscillating Low Pressure Dispense with various Nozzles for DI-H₂O &/or Chemistries.
- Chemical Cabinet with weight Scale Dispense Canisters, Digital Flow Meter & Pump.
- Heater for Chemical & DI-H₂O Dispenses.
- Secondary Containment with Leak Detection
- Point of Use Mixing Systems.
- Expandable Recipe & Recipe Storage.
- FM4910 Fire Retardant Cabinet & Process Area Materials
- Chemical Recovery Systems based on multiple diverter

Model RSSx124: • 29.5" wide X 35.25" deep
• Up to Two Process Arms

Model RSSx126: • 34.5" wide X 35.25" deep
• Up to Four Process Arms

valves, pumping to drums, & level sensing.



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